

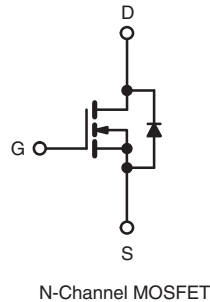
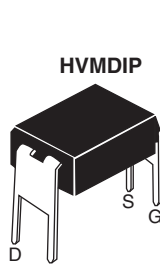


**THE DATASHEET OF
IRLD110PBF**



Power MOSFET

| PRODUCT SUMMARY | | |
|---------------------------|------------------|------|
| V_{DS} (V) | 100 | |
| $R_{DS(on)}$ (Ω) | $V_{GS} = 5.0$ V | 0.54 |
| Q_g (Max.) (nC) | 6.1 | |
| Q_{gs} (nC) | 2.6 | |
| Q_{gd} (nC) | 3.3 | |
| Configuration | Single | |



FEATURES

- Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- For Automatic Insertion
- End Stackable
- Logic-Level Gate Drive
- $R_{DS(on)}$ Specified at $V_{GS} = 4$ V and 5 V
- 175 °C Operating Temperature
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



Note

* Lead (Pb)-containing terminations are not RoHS-compliant. Exemptions may apply.

DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The 4 pin DIP package is a low cost machine-insertable case style which can be stacked in multiple combinations on standard 0.1" pin centers. The dual drain serves as a thermal link to the mounting surface for power dissipation levels up to 1 W.

| ORDERING INFORMATION | |
|----------------------|-------------|
| Package | HVMDIP |
| Lead (Pb)-free | IRLD110PbF |
| | SiHLD110-E3 |
| SnPb | IRLD110 |
| | SiHLD110 |

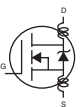

| ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted) | | | | |
|---|-------------------|------------------|------|------|
| PARAMETER | SYMBOL | LIMIT | UNIT | |
| Drain-Source Voltage | V_{DS} | 100 | V | |
| Gate-Source Voltage | V_{GS} | ± 10 | | |
| Continuous Drain Current | V_{GS} at 5.0 V | $T_A = 25$ °C | A | |
| | | $T_A = 100$ °C | | 0.70 |
| Pulsed Drain Current ^a | I_{DM} | 8.0 | | |
| Linear Derating Factor | | 0.0083 | W/°C | |
| Single Pulse Avalanche Energy ^b | E_{AS} | 100 | mJ | |
| Avalanche Current ^a | I_{AR} | 1.0 | A | |
| Repetitive Avalanche Energy ^a | E_{AR} | 0.13 | mJ | |
| Maximum Power Dissipation | $T_A = 25$ °C | P_D | 1.3 | W |
| Peak Diode Recovery dV/dt ^c | dV/dt | 5.5 | V/ns | |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | - 55 to + 175 | °C | |
| Soldering Recommendations (Peak Temperature) | for 10 s | 300 ^d | | |

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 25$ V, starting $T_J = 25$ °C, $L = 6.4$ mH, $R_g = 25$ Ω , $I_{AS} = 5.6$ A (see fig. 12).
- $I_{SD} \leq 5.6$ A, $di/dt \leq 75$ A/ μ s, $V_{DD} \leq V_{DS}$, $T_J \leq 175$ °C.
- 1.6 mm from case.



| THERMAL RESISTANCE RATINGS | | | | |
|-----------------------------|------------|------|------|------|
| PARAMETER | SYMBOL | TYP. | MAX. | UNIT |
| Maximum Junction-to-Ambient | R_{thJA} | - | 120 | °C/W |

| SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted) | | | | | | | |
|---|---------------------|---|---|------|------|-----------|---------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | | MIN. | TYP. | MAX. | UNIT |
| Static | | | | | | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$ | | 100 | - | - | V |
| V_{DS} Temperature Coefficient | $\Delta V_{DS}/T_J$ | Reference to $25\text{ }^\circ\text{C}, I_D = 1\text{ mA}$ | | - | 0.12 | - | V/°C |
| Gate-Source Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$ | | 1.0 | - | 2.0 | V |
| Gate-Source Leakage | I_{GSS} | $V_{GS} = \pm 10\text{ V}$ | | - | - | ± 100 | nA |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = 100\text{ V}, V_{GS} = 0\text{ V}$ | | - | - | 25 | μA |
| | | $V_{DS} = 80\text{ V}, V_{GS} = 0\text{ V}, T_J = 150\text{ }^\circ\text{C}$ | | - | - | 250 | |
| Drain-Source On-State Resistance | $R_{DS(on)}$ | $V_{GS} = 5.0\text{ V}$ | $I_D = 0.60\text{ A}^b$ | - | - | 0.54 | Ω |
| | | $V_{GS} = 4.0\text{ V}$ | $I_D = 0.50\text{ A}^b$ | - | - | 0.76 | |
| Forward Transconductance | g_{fs} | $V_{DS} = 50\text{ V}, I_D = 0.60\text{ A}^b$ | | 1.3 | - | - | S |
| Dynamic | | | | | | | |
| Input Capacitance | C_{iss} | $V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}, \text{ see fig. 5}$ | | - | 250 | - | μF |
| Output Capacitance | C_{oss} | | | - | 80 | - | |
| Reverse Transfer Capacitance | C_{rss} | | | - | 15 | - | |
| Total Gate Charge | Q_g | $V_{GS} = 5.0\text{ V}$ | $I_D = 5.6\text{ A}, V_{DS} = 80\text{ V}, \text{ see fig. 6 and 13}^b$ | - | - | 6.1 | nC |
| Gate-Source Charge | Q_{gs} | | | - | - | 2.6 | |
| Gate-Drain Charge | Q_{gd} | | | - | - | 3.3 | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = 50\text{ V}, I_D = 5.6\text{ A}, R_g = 12\text{ }\Omega, R_D = 8.4\text{ }\Omega, \text{ see fig. 10}^b$ | | - | 9.3 | - | ns |
| Rise Time | t_r | | | - | 4.7 | - | |
| Turn-Off Delay Time | $t_{d(off)}$ | | | - | 16 | - | |
| Fall Time | t_f | | | - | 17 | - | |
| Internal Drain Inductance | L_D | Between lead, 6 mm (0.25") from package and center of die contact  | | - | 4.0 | - | nH |
| Internal Source Inductance | L_S | | | - | 6.0 | - | |
| Drain-Source Body Diode Characteristics | | | | | | | |
| Continuous Source-Drain Diode Current | I_S | MOSFET symbol showing the integral reverse p - n junction diode  | | - | - | 1.0 | A |
| Pulsed Diode Forward Current ^a | I_{SM} | | | - | - | 8.0 | |
| Body Diode Voltage | V_{SD} | $T_J = 25\text{ }^\circ\text{C}, I_S = 1.0\text{ A}, V_{GS} = 0\text{ V}^b$ | | - | - | 2.5 | V |
| Body Diode Reverse Recovery Time | t_{rr} | $T_J = 25\text{ }^\circ\text{C}, I_F = 5.6\text{ A}, di/dt = 100\text{ A}/\mu\text{s}^b$ | | - | 110 | 130 | ns |
| Body Diode Reverse Recovery Charge | Q_{rr} | | | - | 0.50 | 0.65 | μC |
| Forward Turn-On Time | t_{on} | Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D) | | | | | |

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\text{ }\%$.



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

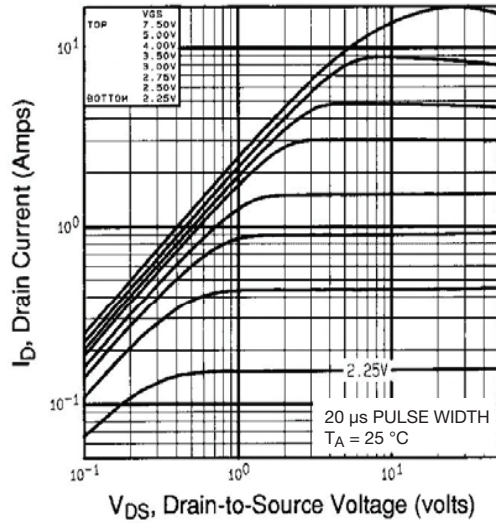


Fig. 1 - Typical Output Characteristics, $T_A = 25\text{ }^\circ\text{C}$

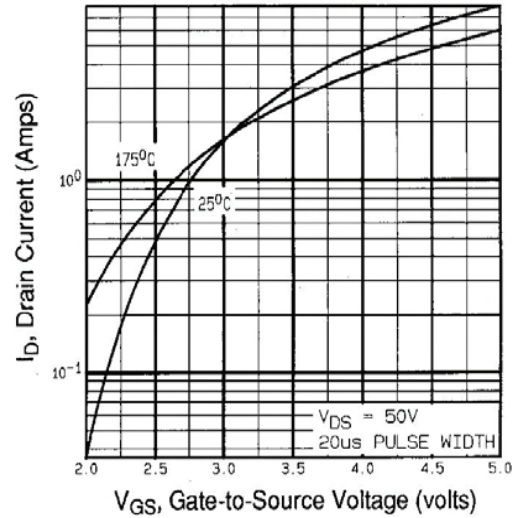


Fig. 3 - Typical Transfer Characteristics

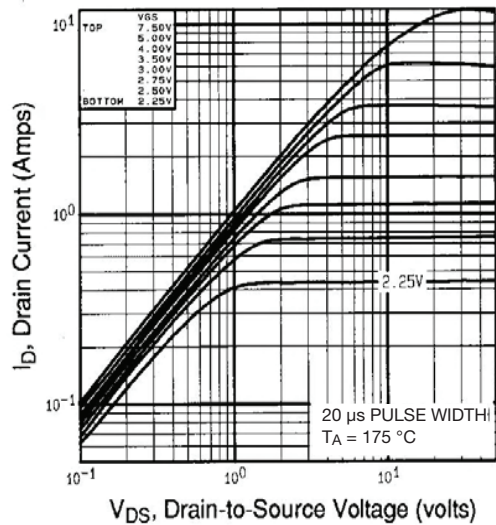


Fig. 2 - Typical Output Characteristics, $T_A = 175\text{ }^\circ\text{C}$

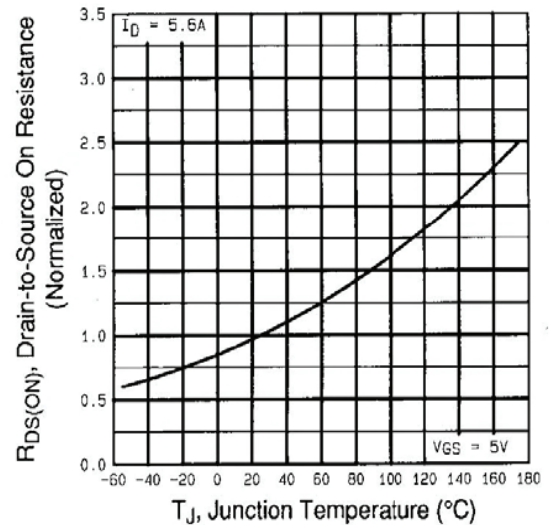


Fig. 4 - Normalized On-Resistance vs. Temperature

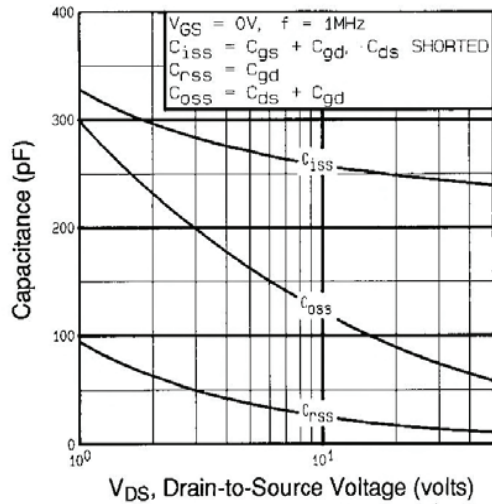


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

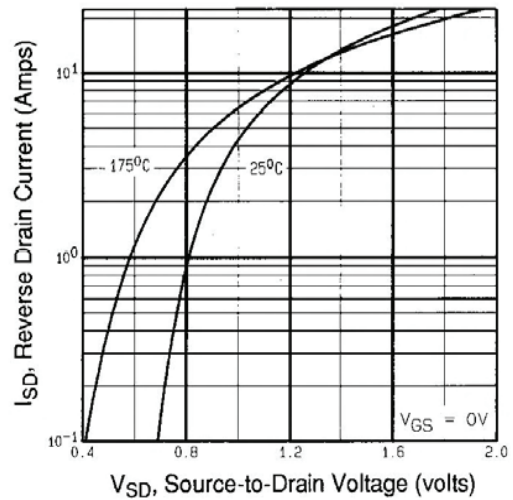


Fig. 7 - Typical Source-Drain Diode Forward Voltage

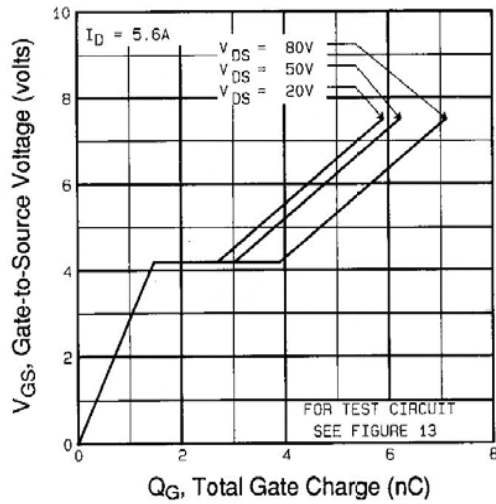


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

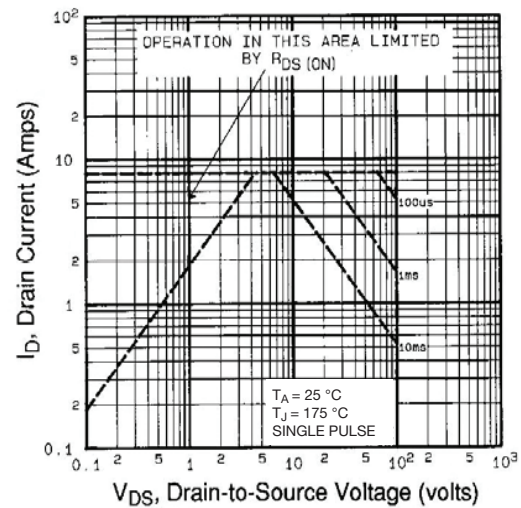


Fig. 8 - Maximum Safe Operating Area

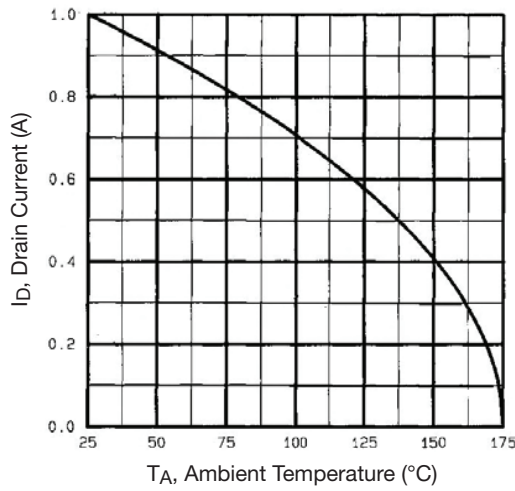


Fig. 9 - Maximum Drain Current vs. Ambient Temperature

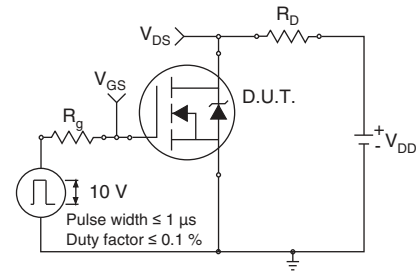


Fig. 10 - Switching Time Test Circuit

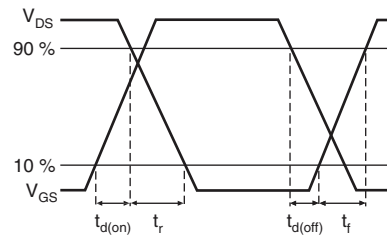


Fig. 11 - Switching Time Waveforms

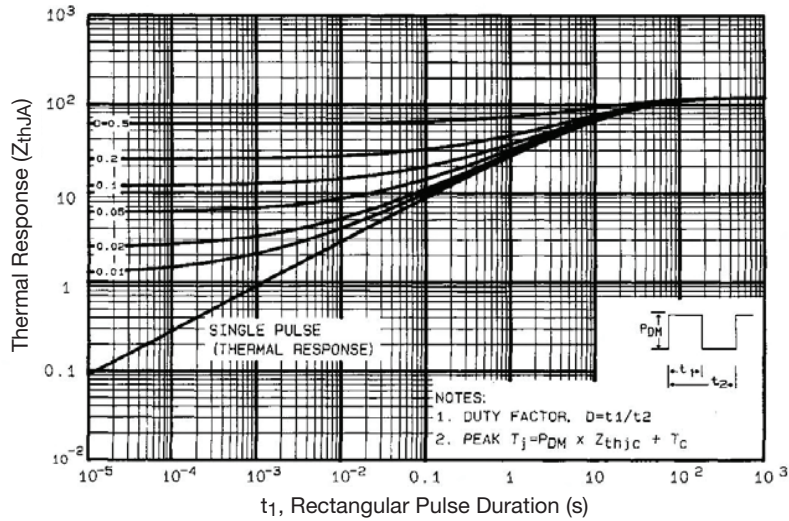


Fig. 12 - Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

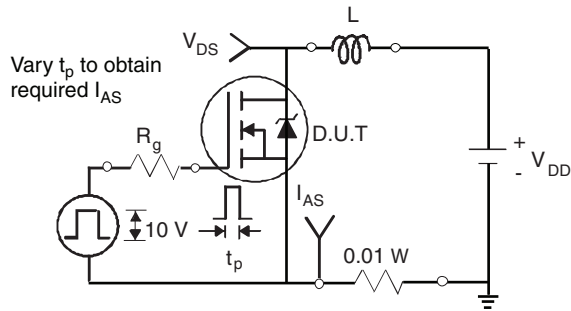


Fig. 13 - Unclamped Inductive Test Circuit

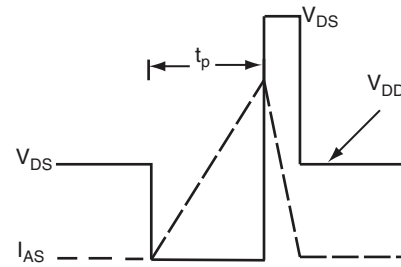


Fig. 14 - Unclamped Inductive Waveforms

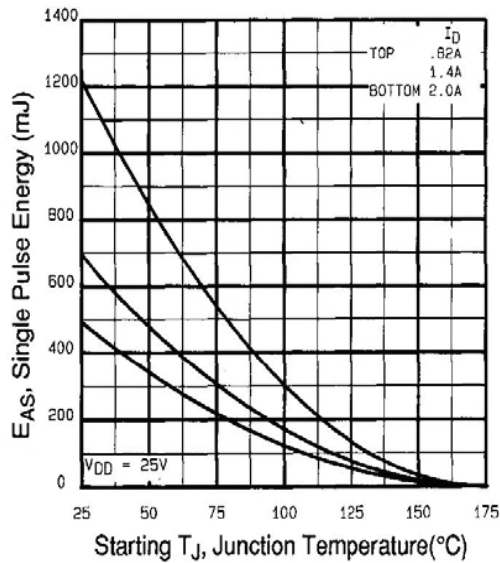


Fig. 15 - Maximum Avalanche Energy vs. Drain Current

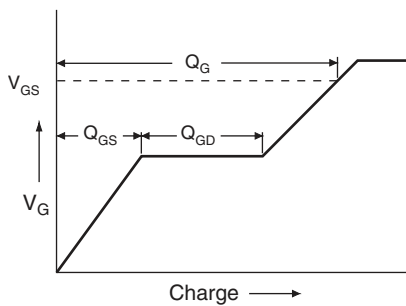


Fig. 16 - Basic Gate Charge Waveform

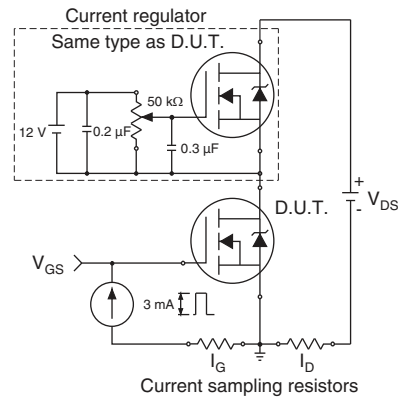
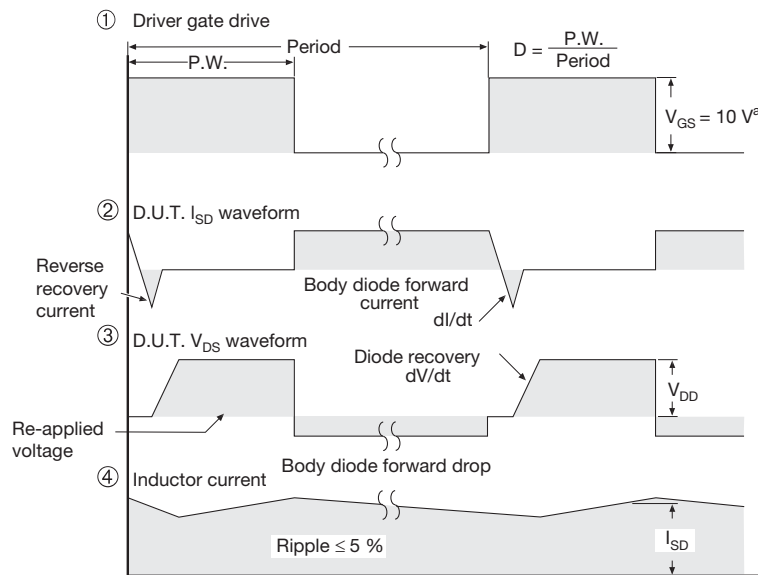
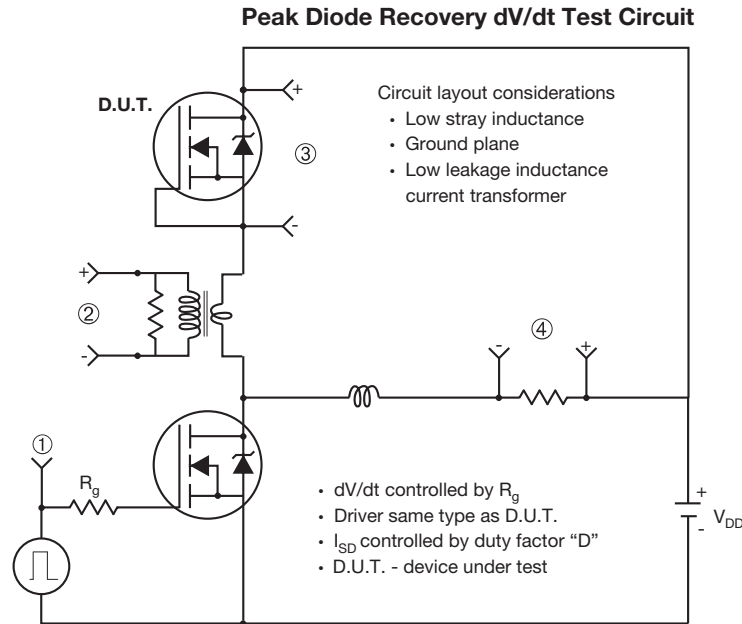


Fig. 17 - Gate Charge Test Circuit



Note

a. $V_{GS} = 5\text{ V}$ for logic level devices

Fig. 18 - For N-Channel

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HVM DIP (High voltage)



| DIM. | INCHES | | MILLIMETERS | |
|------|--------|-------|-------------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 0.310 | 0.330 | 7.87 | 8.38 |
| E | 0.300 | 0.425 | 7.62 | 10.79 |
| L | 0.270 | 0.290 | 6.86 | 7.36 |

ECN: X10-0386-Rev. B, 06-Sep-10
DWG: 5974

Note

- Package length does not include mold flash, protrusions or gate burrs. Package width does not include interlead flash or protrusions.



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